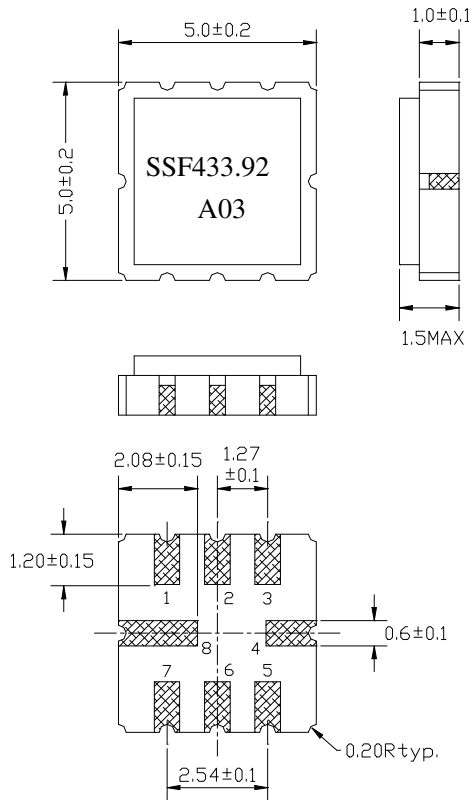


Part No.: SSF433.92A03S5050

1.Package Dimension

(S5050)

Unit: mm



Pin No.	Function
2.	Input
1.	Input Ground
5.	Output
6.	Output Ground
4,8	Case Ground
Other	Ground

2.Marking

SSF433

• F5

- (1) S:STRONG
- (2) SF433.92: Model code
- (3) A03: Series code
- (4) • : Pin 1 Identifier
- (5) F5: Date code

F
Month code

5
Last figure of year

Month	1	2	3	4	5	6	7	8	9	10	11	12
Month code	A	B	C	D	E	F	G	H	I	J	K	L

e.g.: “F5 ” means June of 2005

3. Performance

3.1 Application

RF Low-loss SAW Filter for Wireless Remote Controller Receivers.

Center frequency(f_0): 433.92MHz

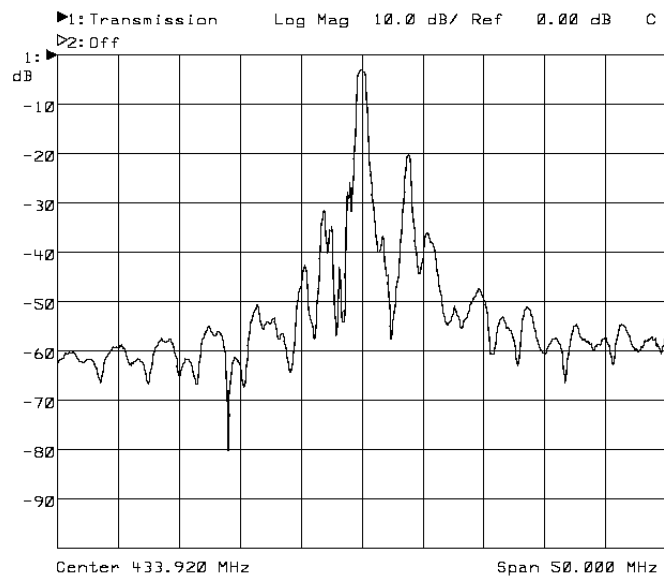
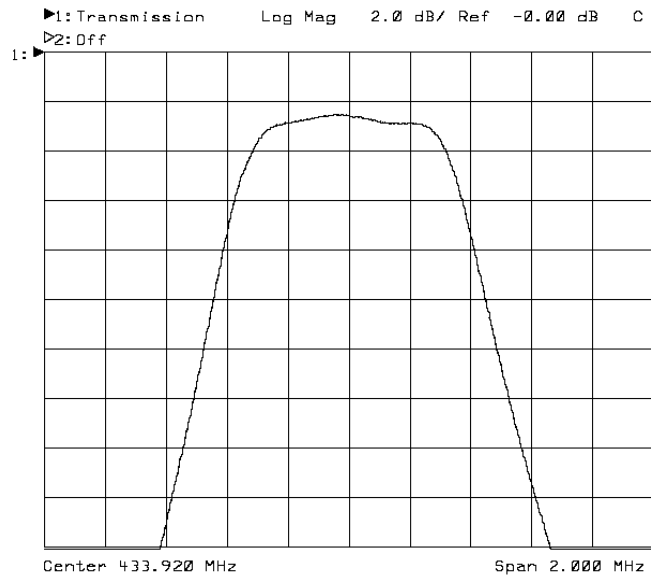
3.2 Maximum Rating

DC Voltage V_{DC}	10V
AC Voltage V_{pp}	10V (50Hz / 60Hz)
Operation Temperature Range	-40°C to +85°C
Storage Temperature Range	-45°C to +85°C
Source Power	10dBm

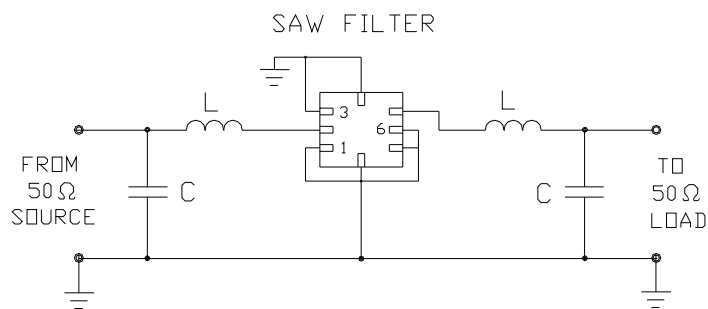
3.3 Electronic Characteristics

Item	Units	Minimum	Typical	Maximum
Center Frequency (f_0)	MHz	---	433.92	---
Insertion Loss 433.80MHz ~ 434.120MHz	dB	---	2.0	4.5
Pass Band Ripple 433.76MHz ~ 434.16MHz	dB	---	1.0	2.0
Relative Attenuation 10.00MHz ~ 414.00MHz	dB	45.0	50.0	---
414.00MHz ~ 428.00MHz	dB	40.0	45.0	---
428.00MHz ~ 432.92MHz	dB	15.0	20.0	---
434.92MHz ~ 442.00MHz	dB	10.0	15.0	---
442.00MHz ~ 550.00MHz	dB	35.0	40.0	---
550.00MHz ~ 1000.00MHz	dB	45.0	50.0	---
Temperature Coefficient of Frequency	ppm/K ²	---	-0.03	---
External Impedance Match Series Inductance L	nH	---	33	---
Shunt Capacitance C	pF	---	5.6	---

3.4 Frequency Characteristics



3.5 Test Circuit



4. Reliability

- 4.1 Mechanical Shock: The components shall remain within the electrical specifications after three one-half sine shock pulses(3000g's for 0.3ms) in each direction(for six total) along each of the three mutually perpendicular axes for a total of 18 shocks.
- 4.2 Vibration Fatigue: The components shall remain within the electrical specifications after loaded vibration at 20~55Hz, amplitude 1.5mm, X,Y,Z, direction, for 2 hours.
- 4.3 Leak Test
- 4.3.1 Gross Leak Test: Submerge samples into at +85°C water for at least 1 minute. Carefully observe the samples. No bubbles should be seen.
- 4.3.2 Fine Leak Test: Expose samples for testing to 60 PSIG Helium gas for 2 hours. Then transfer the same samples to another chamber and draw a vacuum. Measure the leak rate. Failure is defined if the leak rate exceeds 5×10^{-8} atm cc/sec Helium.
- 4.4 High Temperature Storage: The components shall remain within the electrical specifications after being kept at the $85^{\circ}\text{C} \pm 2^{\circ}\text{C}$ for 960 hours, then kept at room temperature for 2 hours.
- 4.5 Low Temperature Storage: The components shall remain within the electrical specifications after being kept at the $-40^{\circ}\text{C} \pm 2^{\circ}\text{C}$ for 960 hours, then kept at room temperature for 2 hours.
- 4.6 Temperature Cycle: The components shall remain within the electrical specification after 32 cycles of high and low temperature testing (one cycle: 80°C for 30 minutes \rightarrow 25°C for 20 seconds \rightarrow -40°C for 30 minutes) than kept at room temperature for 2 hours.
- 4.7 Humidity Test: The components shall remain within the electrical specifications after being kept at the condition of ambient temperature 70°C , and 90~95% RH for 240 hours, then kept at room temperature and normal humidity for 4 hours.
- 4.8 Solder-heat Resistance: The components shall remain within the electrical specifications after dipped in the solder at $260^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 10 to 11 seconds, then kept at room temperature for 10 minutes.
- 4.9 Solderability: Solderability of terminal shall be kept at more than 80% after dipped in the solder flux at $230^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 5 ± 1 seconds.
- 4.10 Storage: The components shall meet the electrical and mechanical specifications after 5 years storage, if stored within the temperature range of $-40^{\circ}\text{C} \sim +85^{\circ}\text{C}$ and in the humidity of 20 to 60% r.h.

5. Remarks

5.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

5.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning.

5.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.

6. Packing

6.1 Dimensions

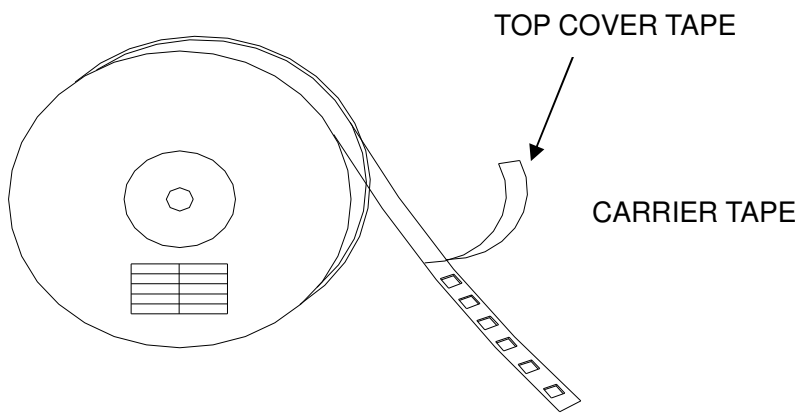
- (1) Carrier Tape: Figure 1
- (2) Reel: Figure 2
- (3) The product shall be packed properly not to be damaged during transportation and storage.

6.2 Reeling Quantity

1,000 pcs/reel

6.3 Taping Structure

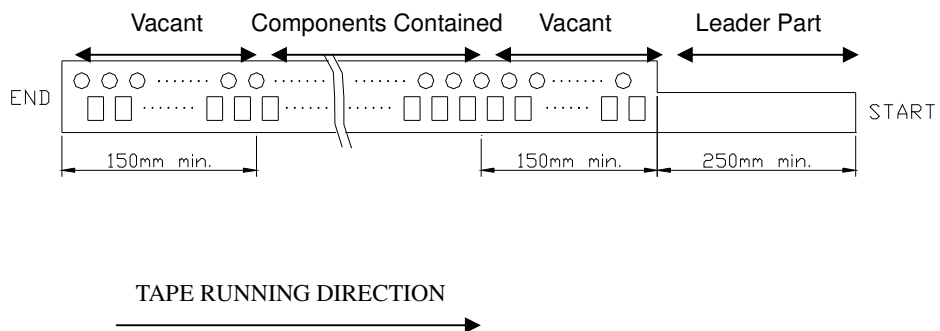
- (1) The tape shall be wound around the reel in the direction shown below.



- (2) Label

Device Name	
Type	
Quantity	
Lot No.	

- (3) Leader part and vacant position specifications.

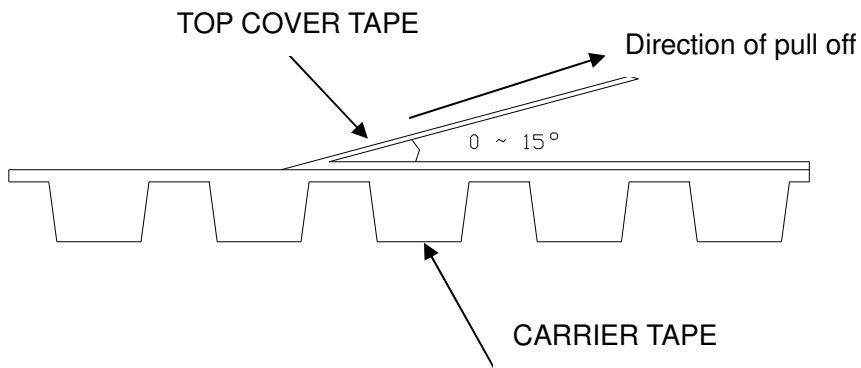


7. Tape Specifications

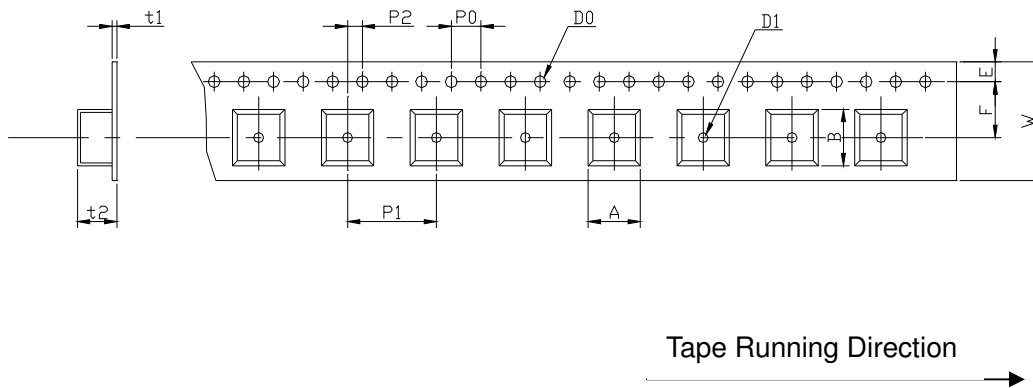
7.1 Tensile Strength of Carrier Tape: 4.4N/mm width

7.2 Top Cover Tape Adhesion (See the below figure)

- (1) pull off angle: 0~15°
- (2) speed: 300mm/min.
- (3) force: 20~70g



[Figure 1] Carrier Tape Dimensions

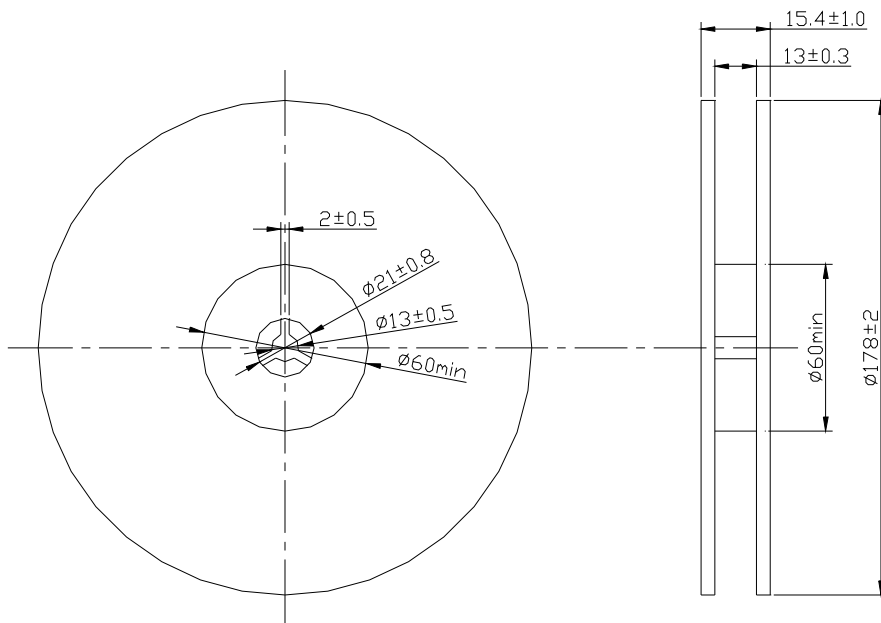


[Unit: mm]

W	F	E	P0	P1	P2	D0	D1	t1	t2	A	B
12.0	5.5	1.75	4.0	8.0	2.0	Φ 1.5	Φ 1.5	0.31	1.95	5.5	5.5
±0.3	±0.1	±0.1	±0.2	±0.1	±0.2	±0.1	±0.25	max.	max.	max.	max.

[Figure 2] Reel Dimensions

[Unit: mm]



[Figure 3] Part Direction

